

ANTREX Electronics

Electronic Components Sourcing Information

Product Reference Information

Part Number:	MPSA06,116
Manufacturer:	NXP USA Inc.
Package:	TO-226-3, TO-92-3 (TO-226AA) Formed Leads
Availability:	Please confirm with sales

Product Page:

<https://antrexco.com/product/details/nxp-usa-inc/mpsa06-116.html>

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Supplier verification and packaging condition review

CoC / RoHS / REACH documents available on request

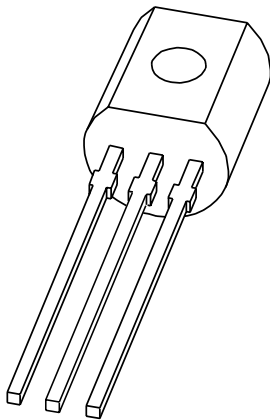
Secure sourcing support for OEM / EMS projects

Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.

DATA SHEET



MPSA06

NPN general purpose transistor

Product specification
Supersedes data of 1999 Apr 27

2004 Oct 11

NPN general purpose transistor

MPSA06

FEATURES

- Low current (max. 500 mA)
- Low voltage (max. 80 V).

APPLICATIONS

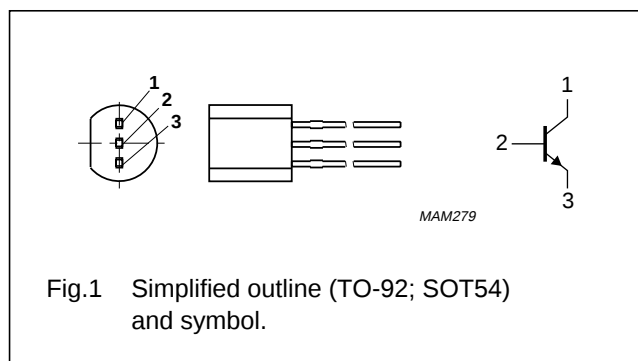
- General purpose switching and amplification.

DESCRIPTION

NPN transistor in a TO-92; SOT54 plastic package.
PNP complement: MPSA56.

PINNING

PIN	DESCRIPTION
1	collector
2	base
3	emitter



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
MPSA06	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	—	80	V
V_{CEO}	collector-emitter voltage	open base	—	80	V
V_{EBO}	emitter-base voltage	open collector	—	5	V
I_C	collector current (DC)		—	500	mA
I_{CM}	peak collector current		—	1	A
I_{BM}	peak base current		—	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$; note 1	—	625	mW
T_{stg}	storage temperature		−65	+150	°C
T_j	junction temperature		—	150	°C
T_{amb}	ambient temperature		−65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

NPN general purpose transistor

MPSA06

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	200	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	$V_{CB} = 80\text{ V}; I_E = 0\text{ A}$	–	50	nA
I_{EBO}	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_C = 0\text{ A}$	–	50	nA
h_{FE}	DC current gain	$V_{CE} = 1\text{ V}; I_C = 10\text{ mA}$	100	–	
		$V_{CE} = 1\text{ V}; I_C = 100\text{ mA}$	100	–	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 100\text{ mA}; I_B = 10\text{ mA}$	–	250	mV
V_{BE}	base-emitter voltage	$V_{CE} = 1\text{ V}; I_C = 100\text{ mA}$	–	1.2	V
f_T	transition frequency	$V_{CE} = 2\text{ V}; I_C = 10\text{ mA}; f = 100\text{ MHz}$	100	–	MHz

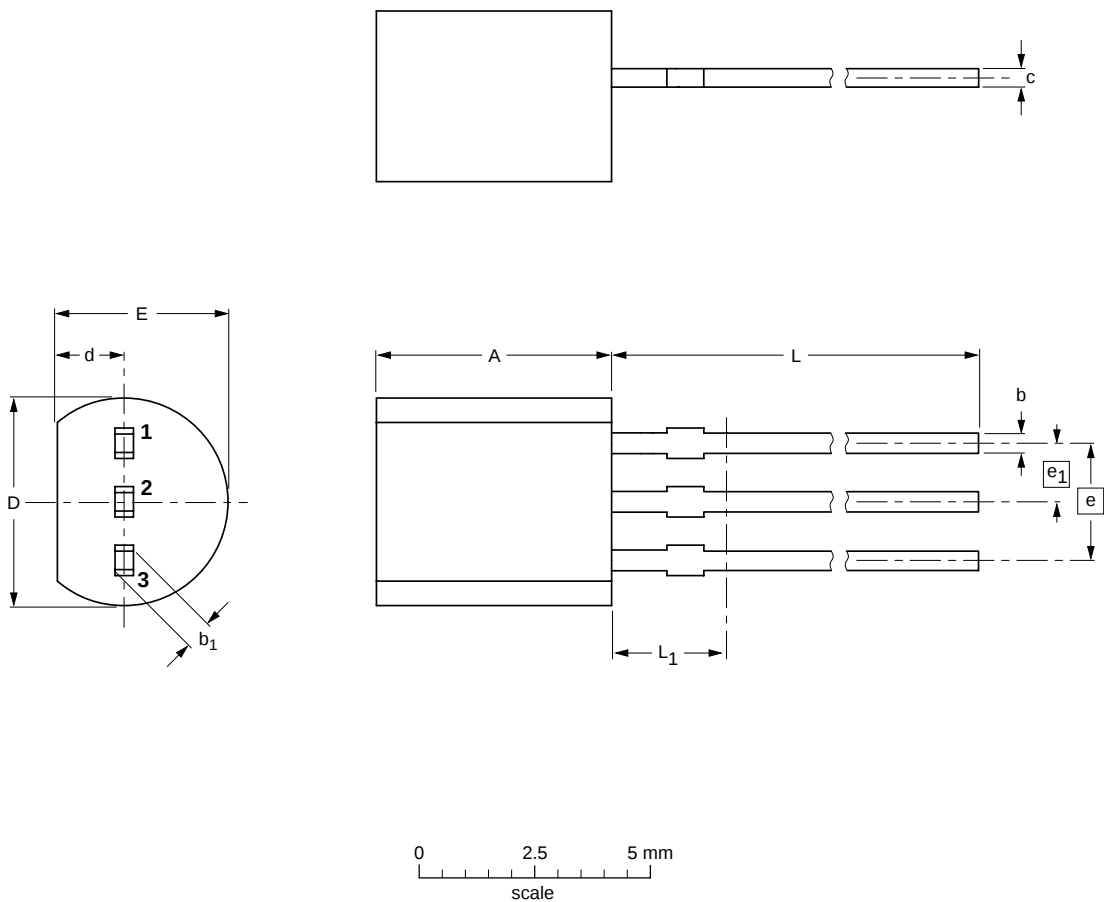
NPN general purpose transistor

MPSA06

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b ₁	c	D	d	E	e	e ₁	L	L ₁ ⁽¹⁾ max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT54		TO-92	SC-43A			-97-02-28 04-06-28

NPN general purpose transistor

MPSA06

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.
3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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